

A Letter of Difference letter

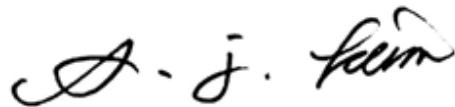
Dear Sir,

This letter is to provide the difference in two main board (Basic: MNX22I1-MAIN_V6R1, Alternative: MNX_22I1-V9R1) which are used for Bluetooth headset model, WEP570.

The difference is as below,

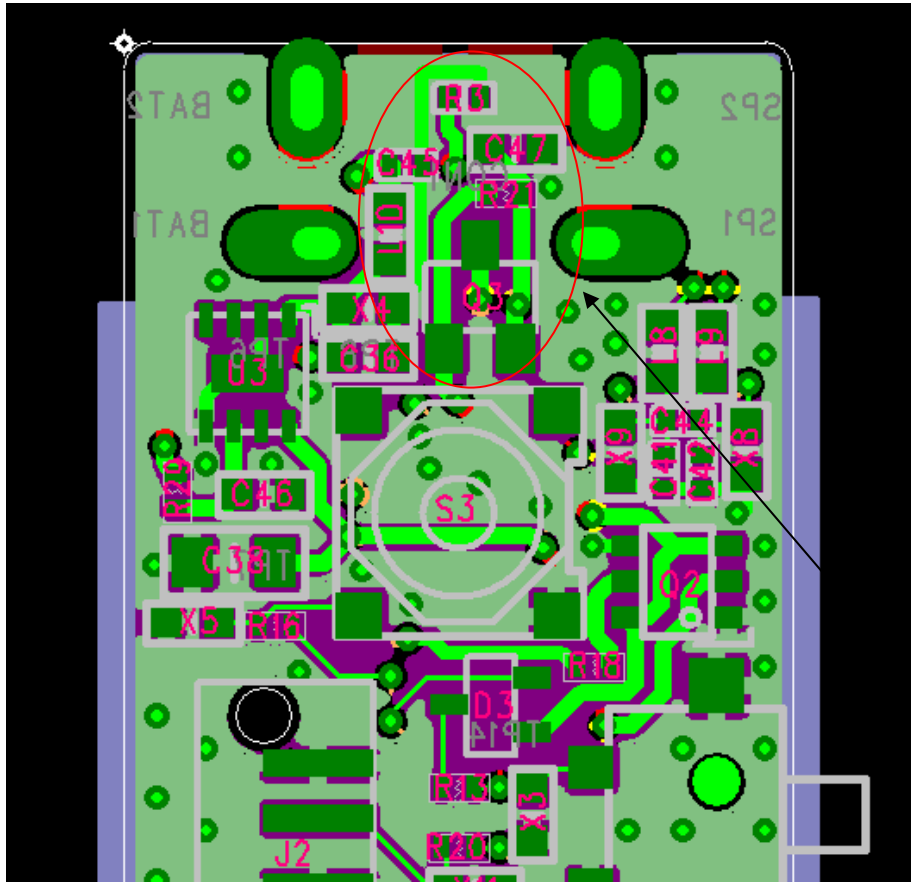
- MFB key: The alternative main board, MNX_22I1-V9R1 has more Q3, L10, R21, C45, R3.
- BAT solder pad: In MNX_22I1-V9R1, BAT solder pad is moved to right side and changed to through hole.

Best Regards

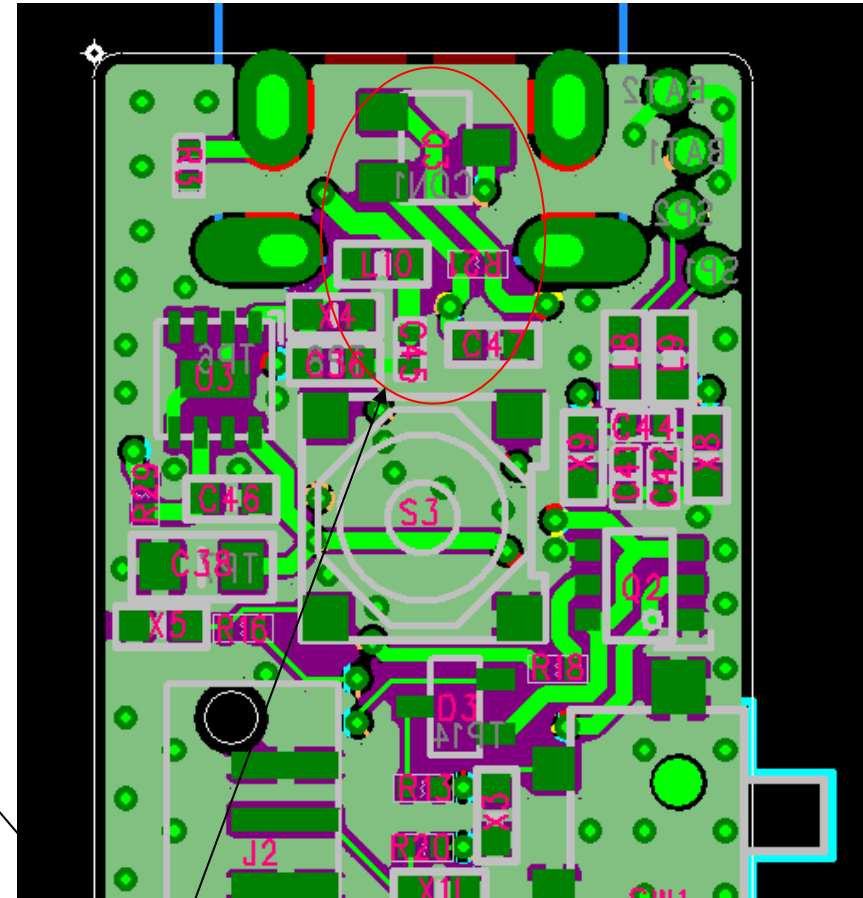
A handwritten signature in black ink, appearing to read "S. J. Kim". The signature is fluid and cursive, with the first letters of each name being capitalized and prominent.

Steve. Kim/ General Manager
Samsung Electronics Co., Ltd.
3, October 2009

Before

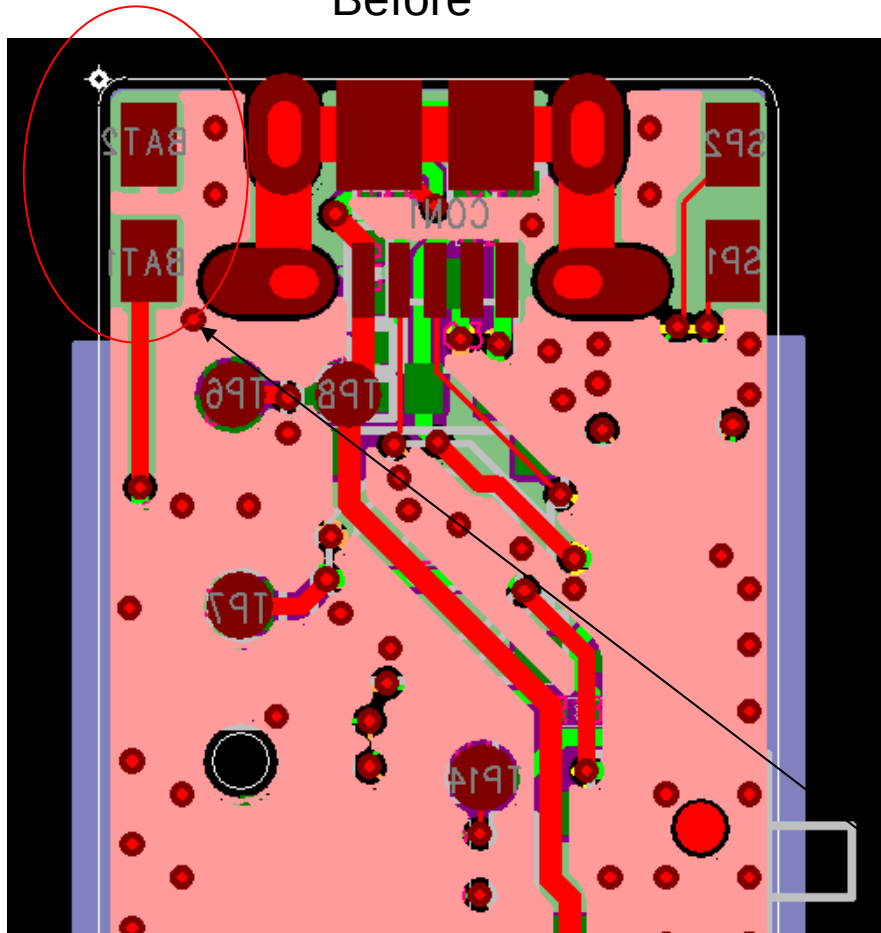


After

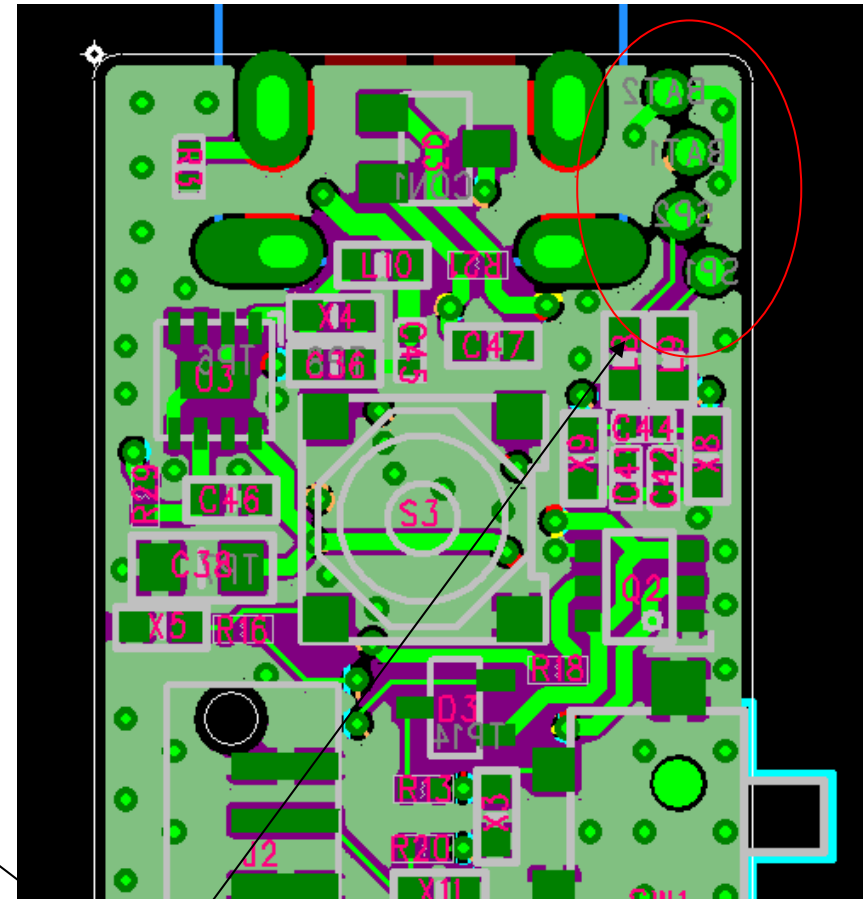


MFB key have interference.
In V9R1 have move Q3,L10,R21,C45,R3

Before



After



BAT solder pad have interference usb cover.
In V9R1 we have move BAT solder pad to right side
and change to through hole.



All soldering pads have 0.5mm distance from edges.

